

Manual Wafer Laminator

L-200 & L-300



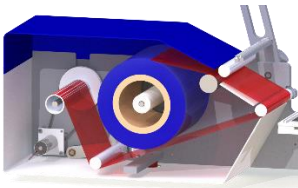
The POWATEC **L-series** are the ideal solutions for air-void-free laminating of wafers. Our customers have relied on these devices for over 20 years to give them high quality results, a great degree of flexibility, and minimal maintenance requirements which is what makes them international industry standards in clean room applications.

The Powatec L-200 and L-300 Manual Wafer Laminators are designed to laminate wafers, up to 300mm, with protective or back-grinding tapes/foils. The wafer is centrally placed on one of our standard or custom chucks and held in place with a vacuum. The mounted laminating tape is then pulled over the wafer and mounting table where it is then applied to the wafer with our patented pad roller, air-void free. The circular cutting device precisely removes the excess tape from the edge of the wafer, and the lateral cutting device separates the tape from the rest of the roll. After peeling the excess tape away and turning off the vacuum, the wafer is now laminated and ready for the next step.

Key Product Features

- ✓ Table-top device
- ✓ Applicable for clean room applications
- ✓ Minimal maintenance (< \$100/year)
- ✓ Lifetime of over 10 years
- ✓ Very short setup times and interchangeable parts make this device especially appealing to high-mix environments
- ✓ Suitable for wafers with and without flats
- ✓ Easily adjust the blade to increase or decrease the amount of excess tape on the edges
- ✓ Output of over 120 wafers/hour
- ✓ Can process Si, SiC, Ge, GaAs, glass, FF4, ceramics, and more

Additional Options



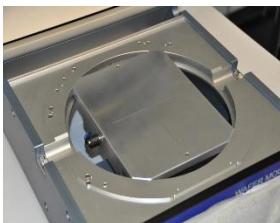
Protection Tape Winder

The protection tape winder is necessary if UV tape is used or if the tape has a protective film. With the PTW option, the protection tape is automatically collected when pulling the tape over the mounting area.



Ionizing Air Bar

Electrostatic charges can be caused by unwinding tape and for applications where these charges must be limited, Powatec offers the Ionizing Air Bar. The bar is installed in proximity to the tape peel-off point where the greatest electrostatic discharge occurs.



Various Chuck Options

Our standard vacuum chucks come in 2", 4", 6", 8", and 300mm. We also offer Non-Contact, Heated, and Ceramic Surface chucks in certain sizes as standard. Custom chucks can also be ordered on request for any shapes and configurations.

Technical Specification

	L-200	L-300
Wafer size	2" to 8"	6" to 300mm
Wafer thickness	50µm to 4.5mm	50µm to 4.5mm
Film/Tape Width	150 to 300 mm	200 to 400 mm
Width	460 mm (18.11")	590 mm (23.22")
Depth	680 mm (26.77")	880 mm (34.64")
<i>With PTW Option</i>	875 mm (34.44")	1000 mm (39.37")
Height	230 mm (9.05")	250 mm (9.84")
Weight	19 kg (41.88 lbs)	25 kg (55.11 lbs)
<i>With PTW Option</i>	25 kg (55.11 lbs)	33 kg (72.75 lbs)
Vacuum requirement	-70 kPa	-70 kPa
Vacuum connection	Outer Diameter = Ø 6 mm	Outer Diameter = Ø 6 mm
Power input		
<i>For PTW Option</i>	85 – 240 VAC	85 – 240 VAC
<i>For ESD Bar Option</i>	115/230 VAC	115/230 VAC
Clean Room Application	Up to ISO 4-5	Up to ISO 4-5
A-weighted emission sound pressure level	does not exceed 70 db(A)	does not exceed 70 db(A)
Peak c-weighted instantaneous sound pressure value at workstations	does not exceed 63 Pa	does not exceed 63 Pa
Conformity	CE Certified	CE Certified

(**Bold** = standard configuration)

Related Products from POWATEC



Manual Wafer Mounter P-300

Mounting of up to 300mm Wafers onto 300mm Film Frames



Vacuum Wafer Mounter V-300

Mounting of up to 300mm Wafer onto 300mm Film Frames



UV LED Wafer Exposure System U-300

UV Curing via LEDs for wafers mounted on frames up to 300mm



Manual Wafer Expansion ETM-300

Wafer expander up to 300mm wafer, frame, and grip ring.